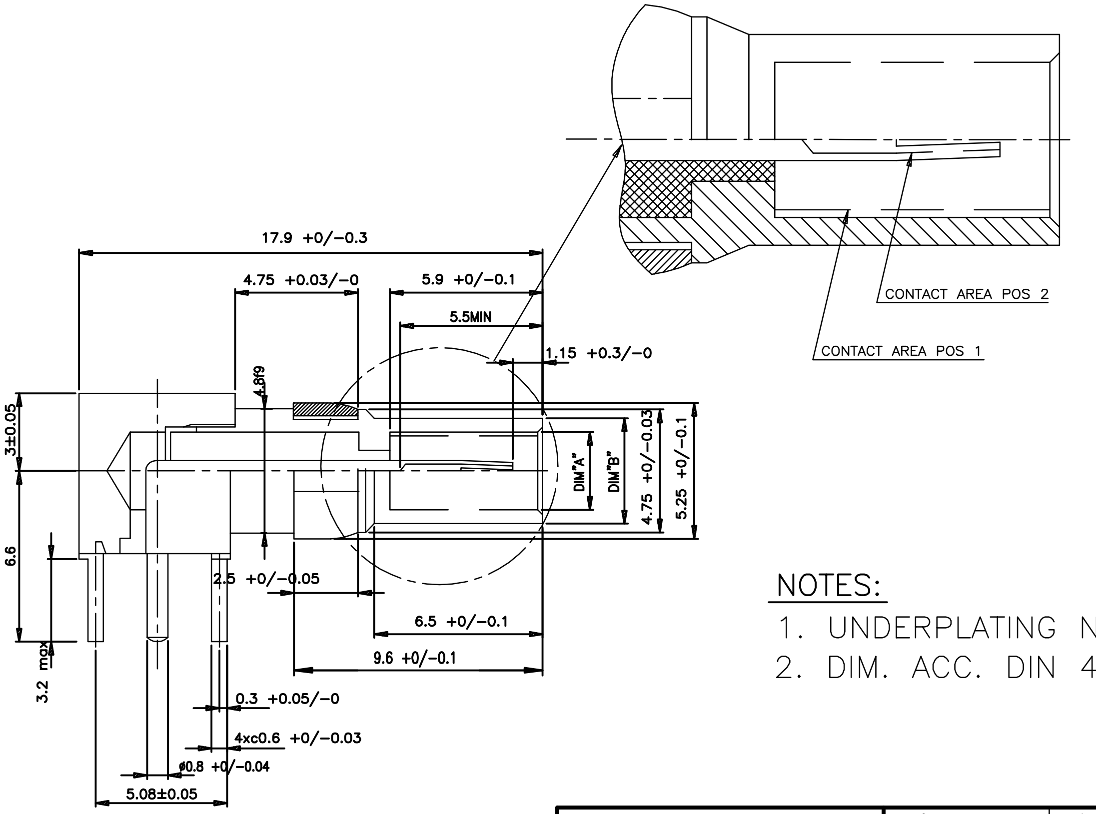
LEAD−FREE P/N	IMPEDANCE	PLATING IN CONTACT AREA		DIM "A"	DIM "B"	
		POS 1	POS 2			
71637−103LF	50 Ohm	1.3 µm Au MIN	1.3 µm Au MIN	3.0/+0.05/−0	4.07/+0/−0.04	
71637−104LF	75 Ohm	1.3 µm Au MIN	1.3 µm Au MIN	3.35/+0.03/−0	4.3/+0.01/−0.03	
71637−104ELF	75 Ohm	1.3 µm Au MIN	1.3 µm Au MIN	3.35/+0.03/−0	4.3/+0.01/−0.03	Order quantity >10000



NOTES:

1. UNDERPLATING Ni.
2. DIM. ACC. DIN 41626

NOTE:RoHS INFORMATIONS

- The "LF" product meets European union Directives and other country regulations as described in GS−22−008.
- The product is not intented to be exposed to a manufacturing solder process.
- Packaging spec: see GS−14−920.

European Views

rev	ecn no	dr	date
G	LS06−0022	LGO	2006/03/06
H	LS07−0214	LGO	2007/08/20
J	LS08−0057	LGO	2008/02/18
K	F11−0306	APA	2011/09/19
L	F12−0030	APA	2012/03/19
−	−	−	−
−	−	−	−

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Dr	GOISNARD	2006/03/06
Eng	GOISNARD	2006/03/06
Chr	LEGARE	2006/03/06
Appr	LEGARE	2006/03/06

surface ISO 1302 ✓

tolerance std ISO 406 ISO 1101

TOLERANCES UNLESS OTHERWISE SPECIFIED

ANGULAR		LINEAR	0.X	±0.1
			0.XX	±0.1
0.XX°	±2°		0.XXX	±0.1

Product family BACKPANEL

projection

mm

size A3

Scale 5

ECN F12−0030

Spec ref −

title FEMALE COAX
INSERT RA STB

catalog no −

dwg no 71637

Rev. L

CUSTOMER

sheet 1 of 1

REV F − 2006−04−17

PDM: Rev:L STATUS:Released Printed: Mar 20, 2012